

Millimeter Wave Flexible Antenna

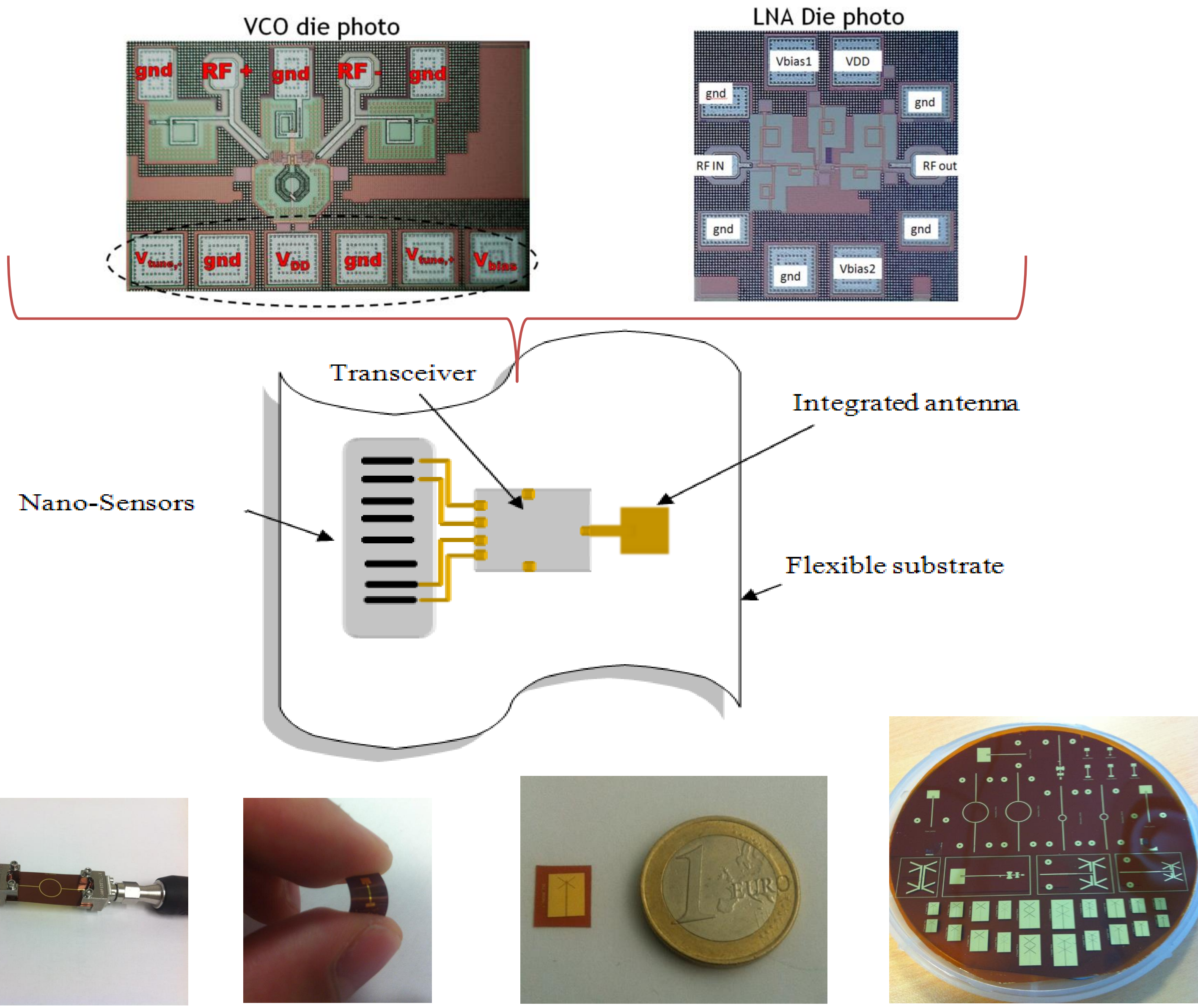
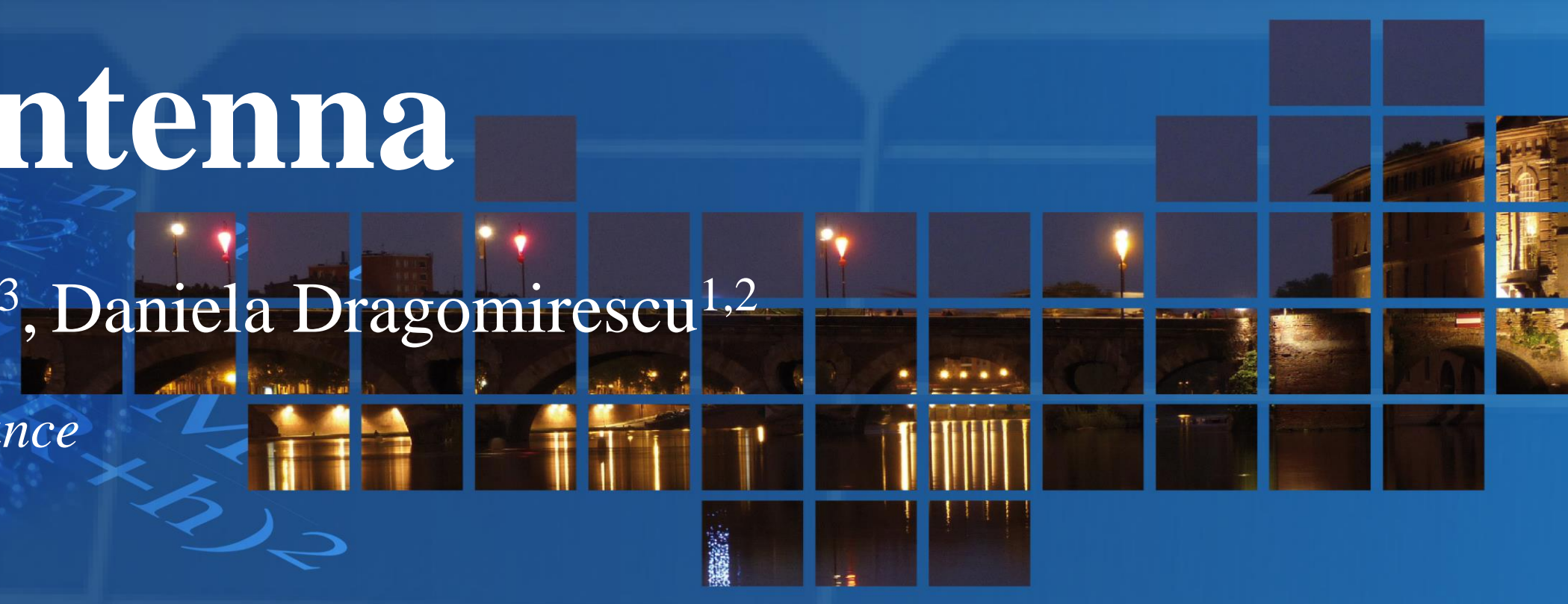
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Laboratoire d'analyse et d'architecture des systèmes



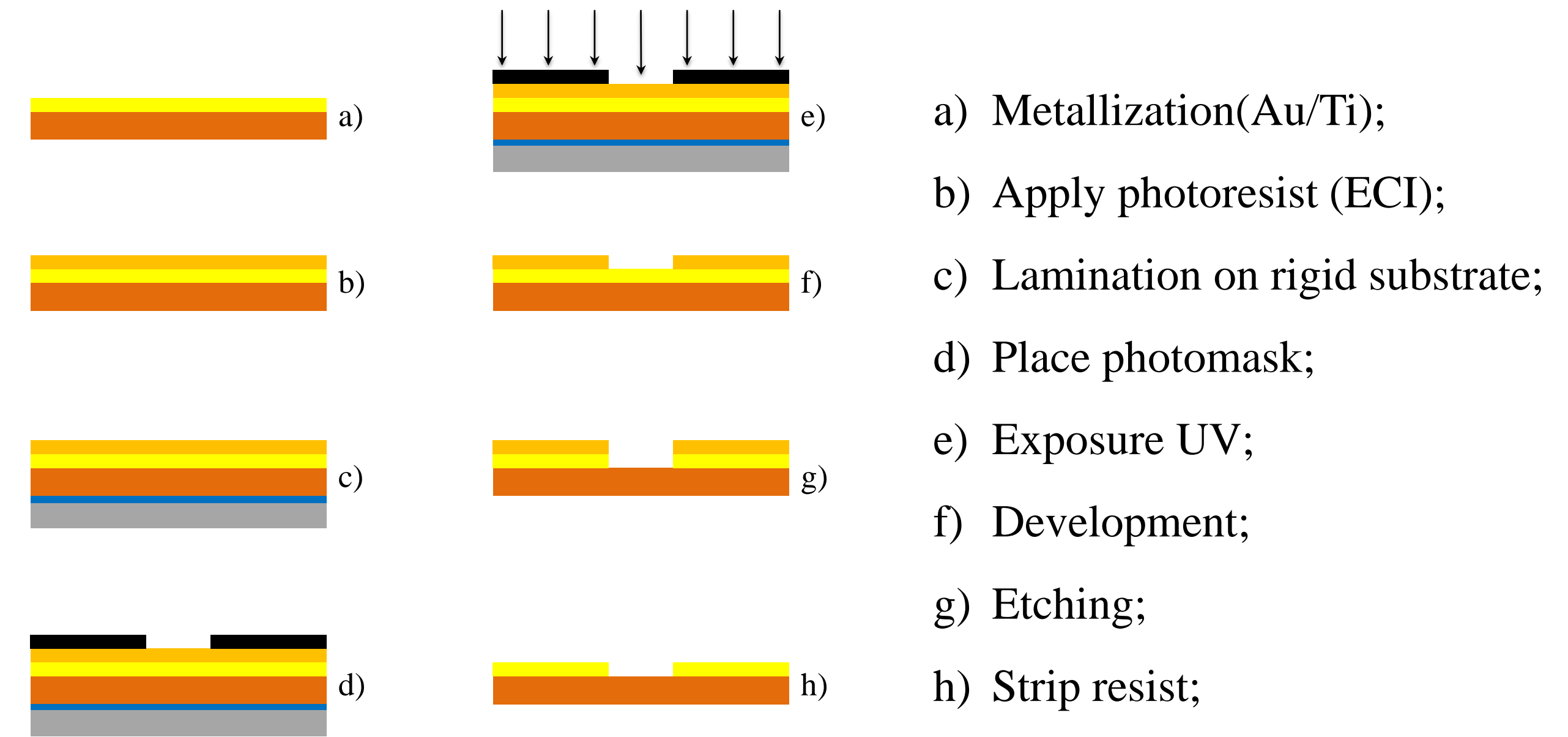
Objective:

- high gain, high efficiency antenna on flexible substrate
- Two types antenna investigated (patch antenna, cross dipole antenna)

State of art:

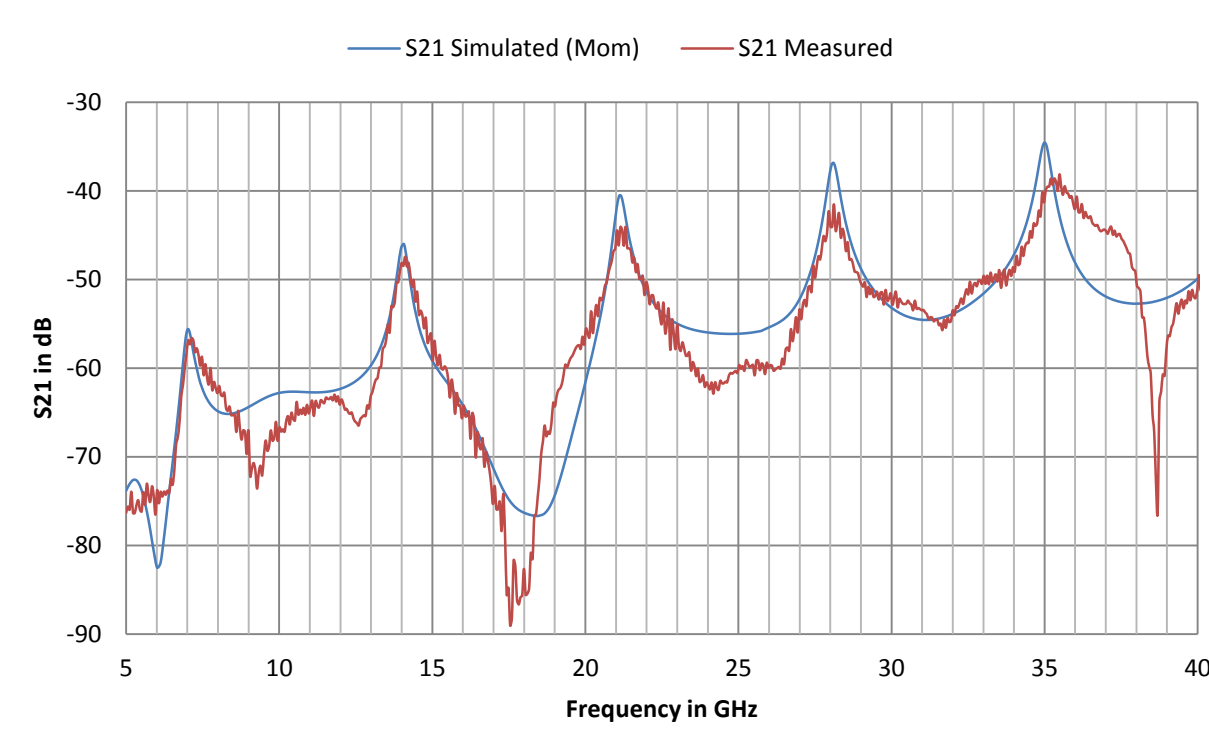
Type of antenna	Substrate	Frequency band	Gain	Author
CPW monopole antenna	PEN	60 GHz	1.8 dB	A.Bisognin, UNS - France
Patch antenna array	LCP	60 GHz	5.3 dB	F.Aryanfar, Caltech - USA
Single patch antenna placed on metal	PEN	60 GHz	7.2 dB	V.Semkin, Aalto ELEC - Finland
Aperture Coupled Patch Antenna	Pyralux	60 GHz	7.9 dB	H.Vettikalladi, IETR - France
Patch antenna array	PDMS	60 GHz	12 dB	S.Hage-AliEMN - France
Patch antenna array	PTFE	60 GHz	14 dB	A.Bondarik, Lund University - Sweden

Processing methods

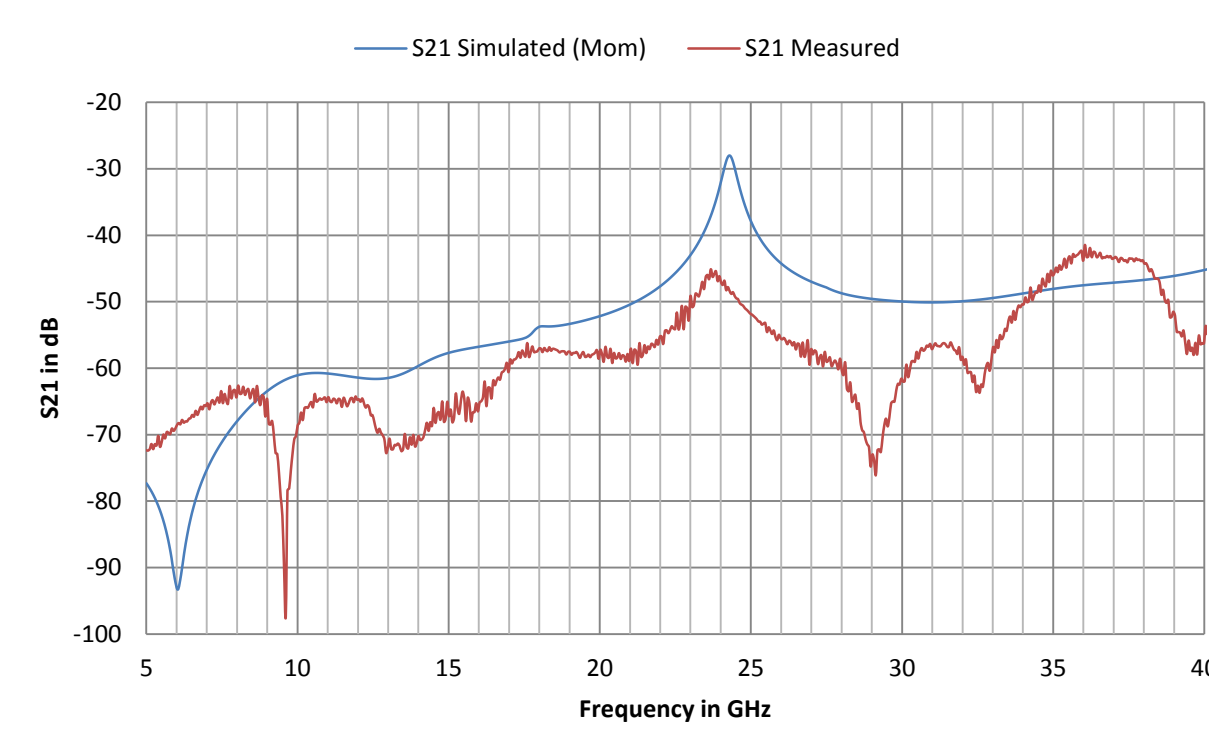


RF characterization of flexible substrate

- 127 μm thickness – avoid effect of capacitance for millimeter wave application
- Antenna performance – good RF properties (permittivity, RF losses) – Kapton 500HN
- Ring resonator method applied (broadband)



Transmission Coefficient of the ring resonator 7GHz



Transmission Coefficient of the ring resonator 24.125GHz

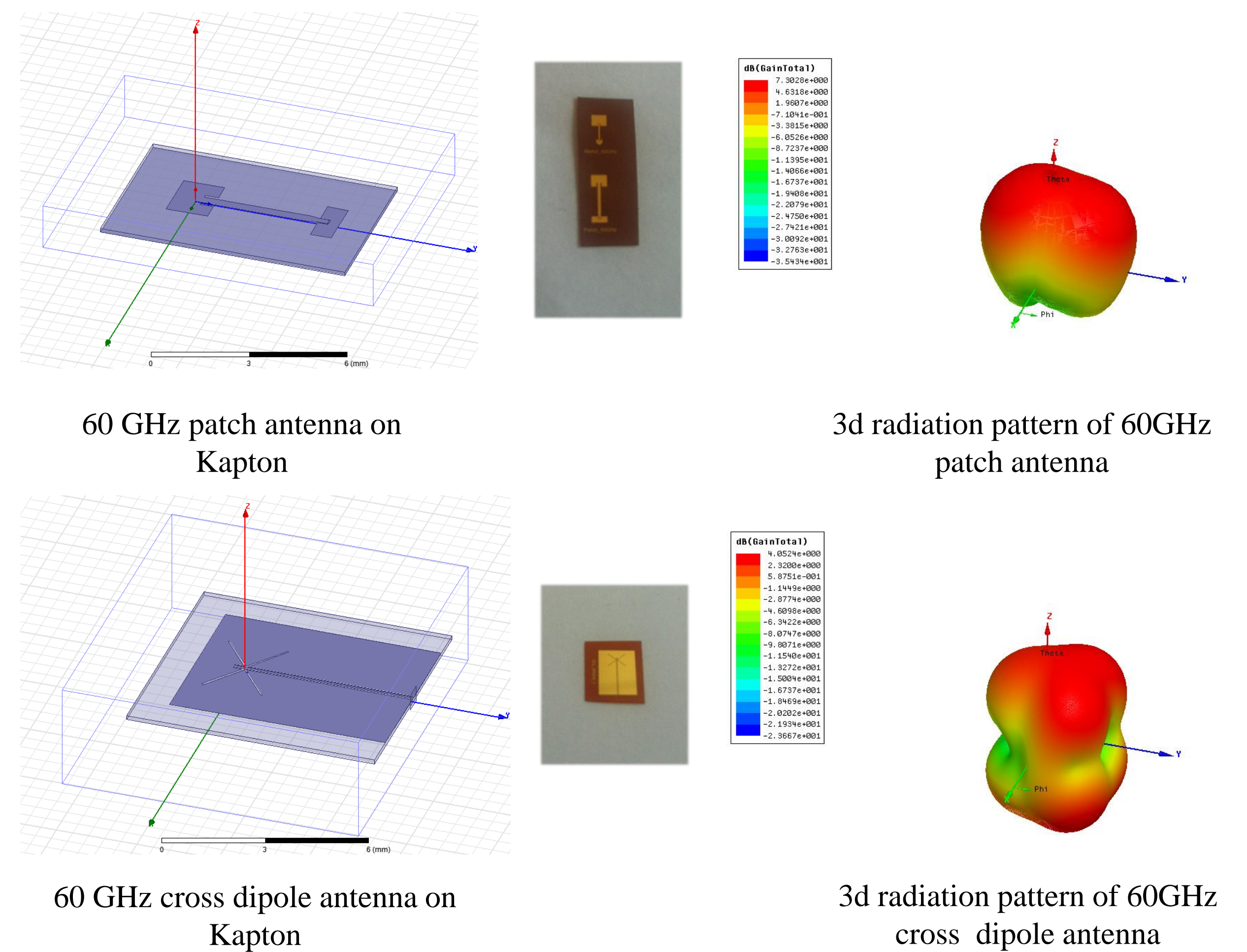
- Measurements matches simulations (ADS Momentum, MoM) from 5GHz to 40GHz

Simulation model validated

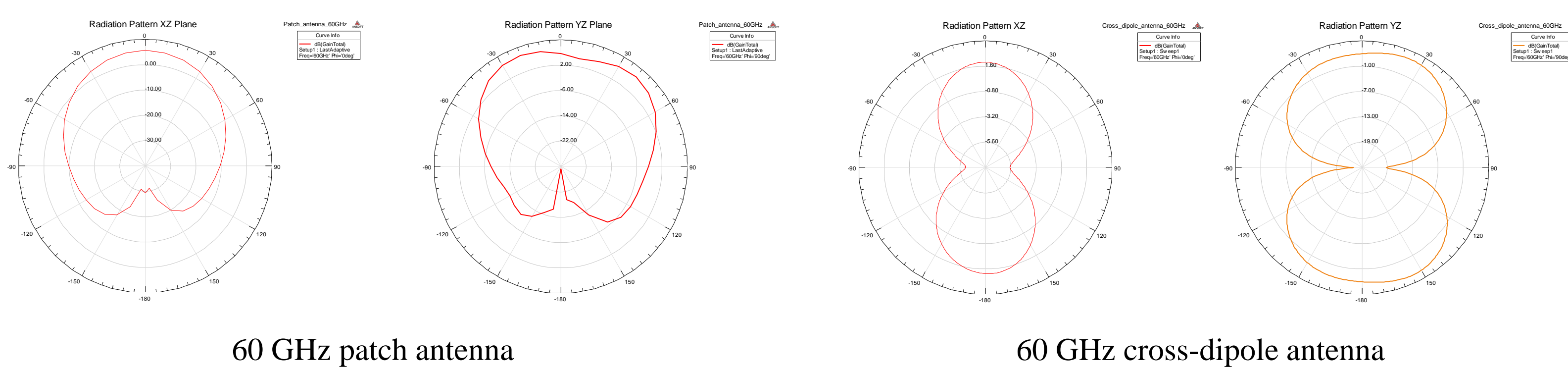
- Relative permittivity = 3.2
- The loss tangent = 0.002

Validated by measurements

Antenna design and simulation (HFSS, FEM)



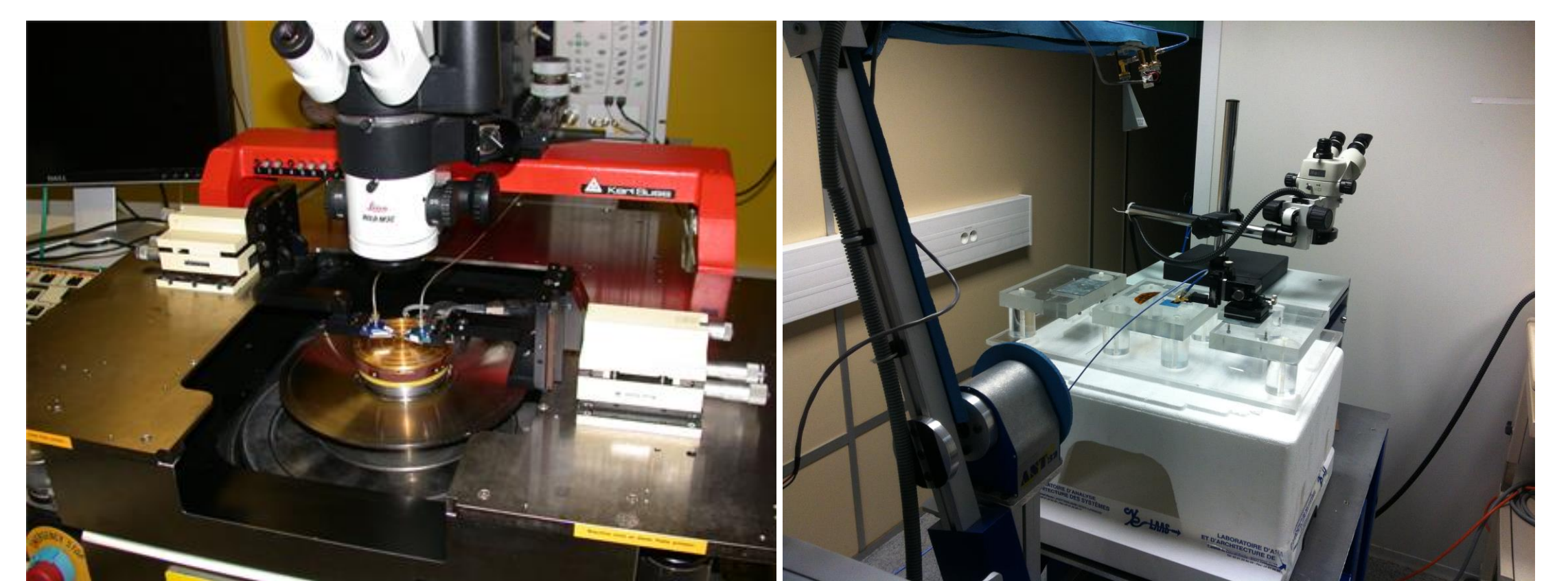
Simulation of far-filed radiation pattern



60 GHz patch antenna

60 GHz cross-dipole antenna

Radiation pattern measurements in progress

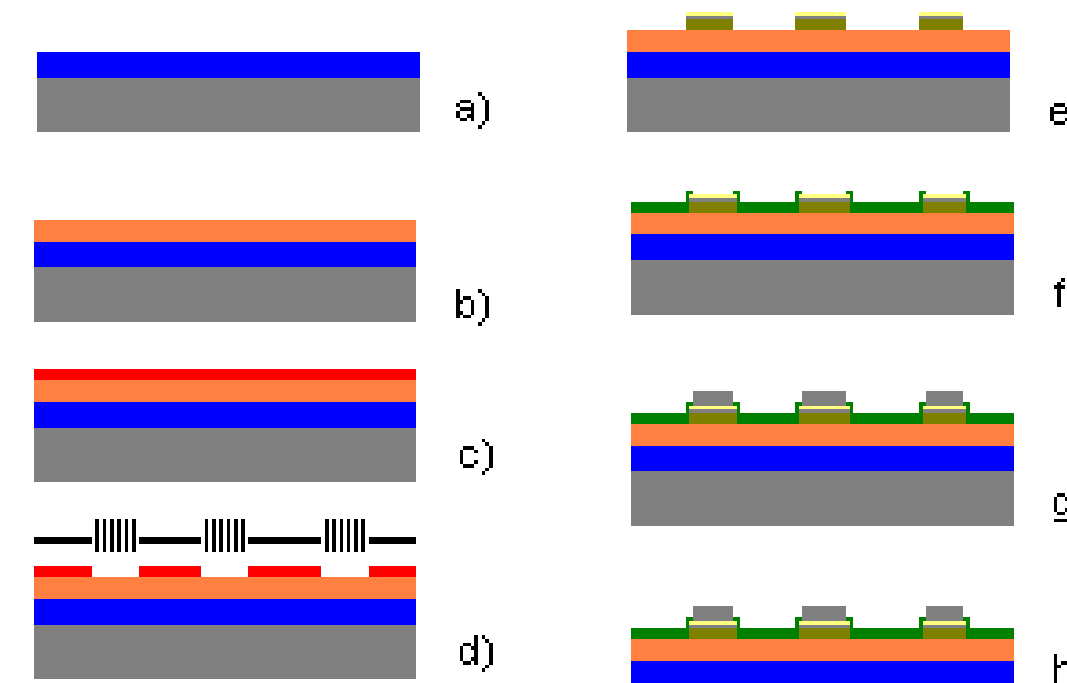


Probe station + rotation arms

Towards 3D heterogeneous integration on flexible substrate wireless sensor nodes

Processing methods

- polymer spin coating for the adhesion;
- polyimide lamination;
- resin lift spin coating;
- photolithography;
- metallization resin stripping by lift off;
- passivation layer;
- soldering screen printing and reflow;
- substrate peeling



Future Work

- High performance and small size antenna
- Fully integration of sensor / transceiver / antenna on flexible substrate